

# 2SC5845

## Silicon NPN epitaxial planar type

For general amplification

### ■ Features

- High forward current transfer ratio  $h_{FE}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

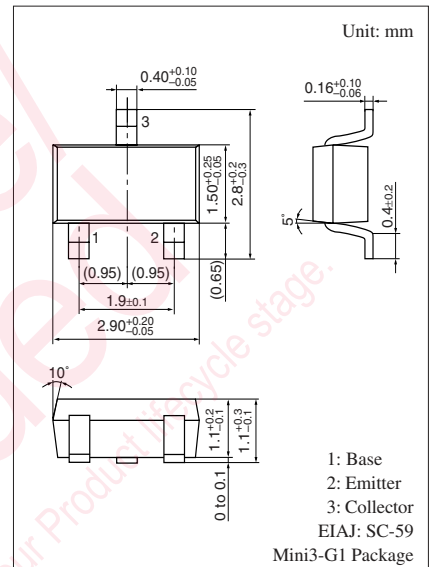
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                             | Symbol    | Rating      | Unit             |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | 60          | V                |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | 50          | V                |
| Emitter-base voltage (Collector open) | $V_{EBO}$ | 7           | V                |
| Collector current                     | $I_C$     | 100         | mA               |
| Peak collector current                | $I_{CP}$  | 200         | mA               |
| Collector power dissipation           | $P_C$     | 200         | mW               |
| Junction temperature                  | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

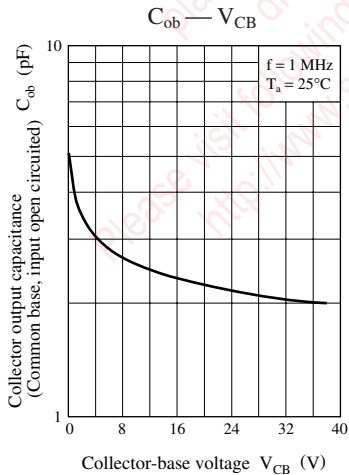
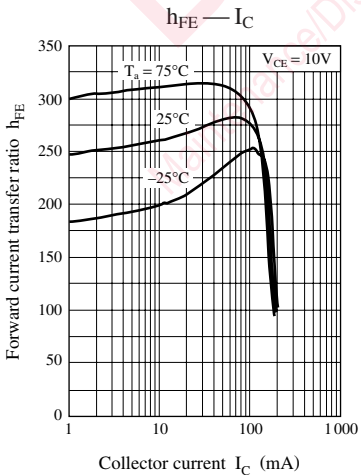
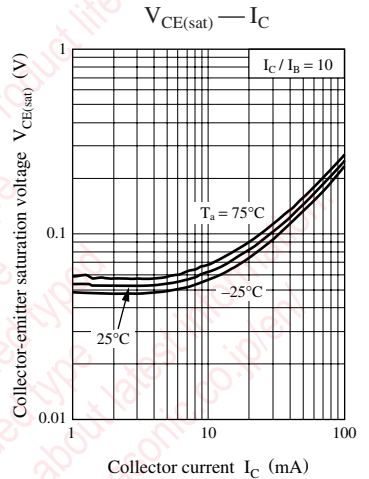
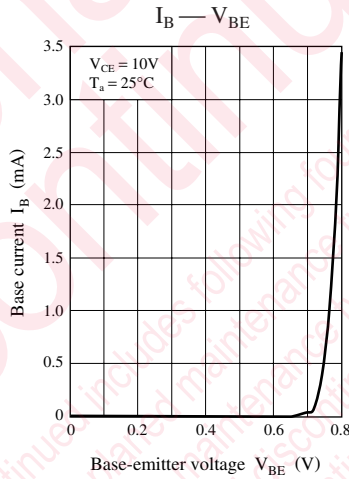
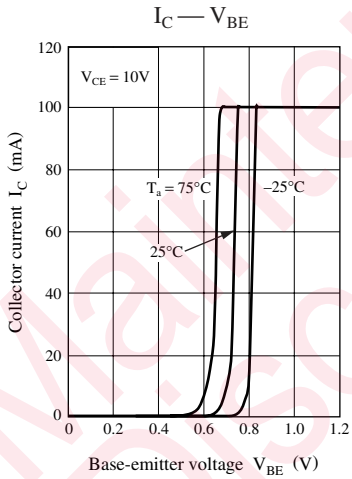
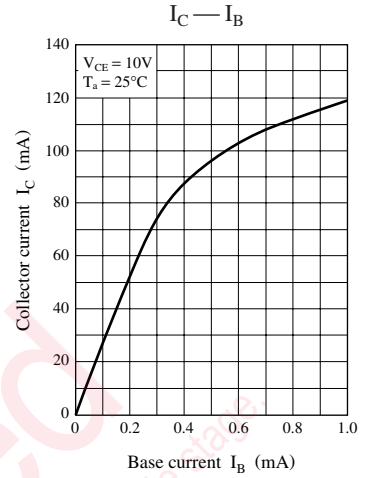
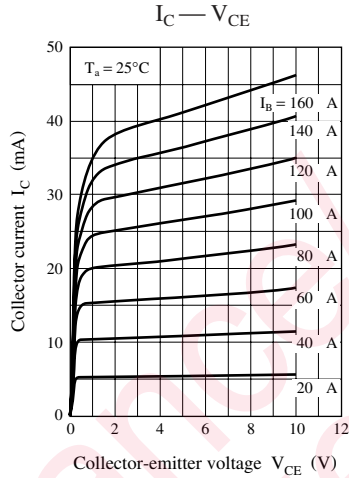
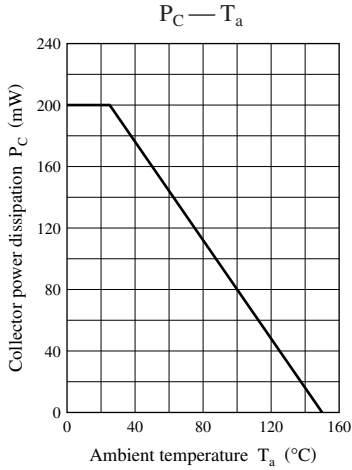
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter  | Symbol        | Conditions   | Min | Typ | Max | Unit          |
|--|---------------|--|-----|-----|-----|---------------|
| Collector-base voltage (Emitter open)                            | $V_{CBO}$     | $I_C = 10 \mu\text{A}, I_E = 0$                                | 60  |     |     | V             |
| Collector-emitter voltage (Base open)                            | $V_{CEO}$     | $I_C = 2 \text{mA}, I_B = 0$                                   | 50  |     |     | V             |
| Emitter-base voltage (Collector open)                            | $V_{EBO}$     | $I_E = 10 \mu\text{A}, I_C = 0$                                | 7   |     |     | V             |
| Collector-base cutoff current (Emitter open)                     | $I_{CBO}$     | $V_{CB} = 20 \text{V}, I_E = 0$                                |     |     | 0.1 | $\mu\text{A}$ |
| Collector-emitter cutoff current (Base open)                     | $I_{CEO}$     | $V_{CE} = 10 \text{V}, I_B = 0$                                |     |     | 100 | $\mu\text{A}$ |
| Forward current transfer ratio                                   | $h_{FE}$      | $V_{CE} = 10 \text{V}, I_C = 2 \text{mA}$                      | 160 |     | 460 | —             |
| Collector-emitter saturation voltage                             | $V_{CE(sat)}$ | $I_C = 100 \text{mA}, I_B = 10 \text{mA}$                      |     | 0.1 | 0.3 | V             |
| Collector output capacitance (Common base, input open circuited) | $C_{ob}$      | $V_{CB} = 10 \text{V}, I_E = 0, f = 1 \text{MHz}$              |     | 2.2 |     | pF            |
| Transition frequency   | $f_T$         | $V_{CB} = 10 \text{V}, I_E = -2 \text{mA}, f = 200 \text{MHz}$ |     | 100 |     | MHz           |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



Marking Symbol: 7M



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